

MBR40250, MBR40250T, MBRF40250T, MBRB40250T

250 V, 40 A SWITCHMODE™ Schottky Power Rectifier

Features

- 250 V Blocking Voltage
- Low Forward Voltage Drop, $V_F = 0.86$ V
- Soft Recovery Characteristic, $T_{RR} < 35$ ns
- Stable Switching Performance Over Temperature
- These are Pb-Free Devices*

Benefits

- Reduces or Eliminates Reverse Recovery Oscillations
- Minimizes Need for EMI Filtering
- Reduces Switching Losses
- Improved Efficiency

Applications

- Power Supply
- Power Management
- Automotive
- Instrumentation

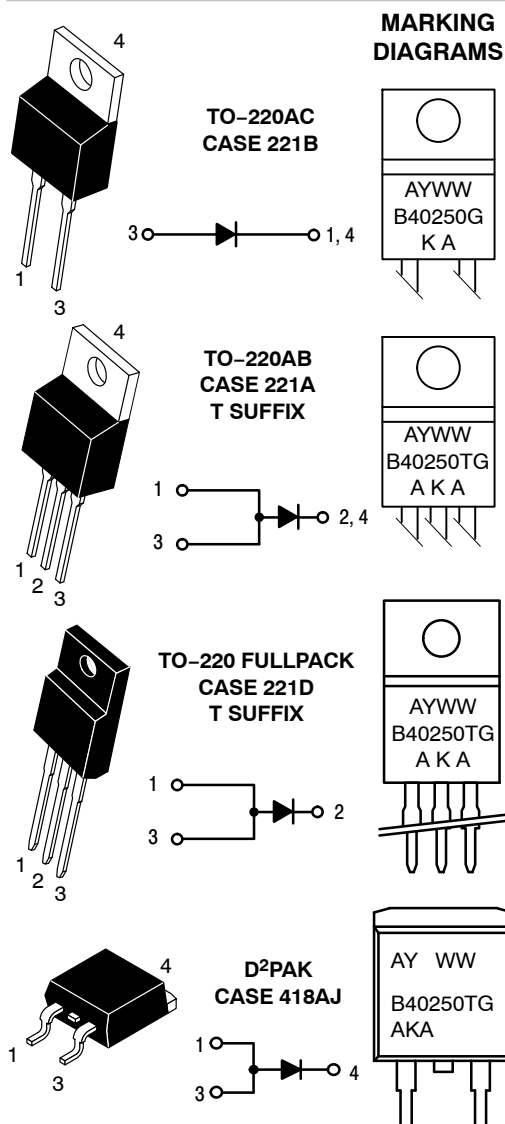
Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 1.9 grams (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes:
260°C Max. for 10 Seconds
- Epoxy Meets UL 94 V-0 at 0.125 in



ON Semiconductor®

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B40250 = Device Code
T = 3 pins
A = Assembly Location
Y = Year
WW = Work Week
G = Pb-Free Package
KA, AKA = Polarity Designator

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	250	V
Average Rectified Forward Current (Rated V_R) $T_C = 82^\circ\text{C}$ MBR40250, MBR40250T, MBRB40250T (Rated V_R) $T_C = 46^\circ\text{C}$ MBRF40250T	$I_{F(AV)}$	40	A
Peak Repetitive Forward Current (Rated V_R , Square Wave, 20 kHz) $T_C = 82^\circ\text{C}$ MBR40250, MBR40250T, MBRB40250T (Rated V_R , Square Wave, 20 kHz) $T_C = 46^\circ\text{C}$ MBRF40250T	I_{FRM}	80	A
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I_{FSM}	150	A
Storage Temperature	T_{stg}	- 65 to +175	$^\circ\text{C}$
Operating Junction Temperature	T_J	- 65 to +150	$^\circ\text{C}$
Voltage Rate of Change (Rated V_R)	dv/dt	10,000	V/ μs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Maximum Thermal Resistance Junction-to-Case MBR40250(T) and MBRB40250T	$R_{\theta JC}$	2.0	$^\circ\text{C/W}$
MBRF40250		3.0	
Junction-to-Ambient MBR40250(T)	$R_{\theta JA}$	60	
MBRF40250		50	
MBRB40250T		50	

ELECTRICAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 1) $I_F = 20\text{ A}$, $T_C = 25^\circ\text{C}$ $I_F = 20\text{ A}$, $T_C = 125^\circ\text{C}$ $I_F = 40\text{ A}$, $T_C = 25^\circ\text{C}$ $I_F = 40\text{ A}$, $T_C = 125^\circ\text{C}$	V_F	0.86 0.71 0.97 0.86	V
Maximum Instantaneous Reverse Current (Note 1) Rated DC Voltage, $T_C = 25^\circ\text{C}$ Rated DC Voltage, $T_C = 125^\circ\text{C}$	I_R	0.25 30	mA
Maximum Reverse Recovery Time $I_F = 1.0\text{ A}$, $di/dt = 50\text{ A}/\mu\text{s}$, $T_C = 25^\circ\text{C}$	t_{rr}	35	ns

DYNAMIC CHARACTERISTICS

Capacitance $V_R = -5.0\text{ V}$, $T_C = 25^\circ\text{C}$, Frequency = 1.0 MHz	C_T	500	pF
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1. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

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TYPICAL CHARACTERISTICS

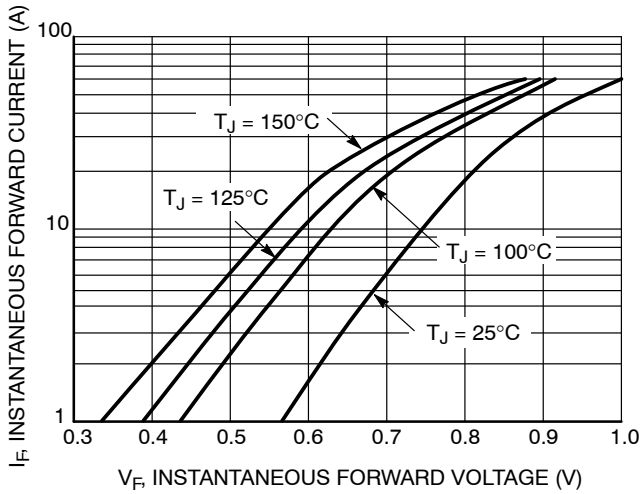


Figure 1. Typical Forward Voltage

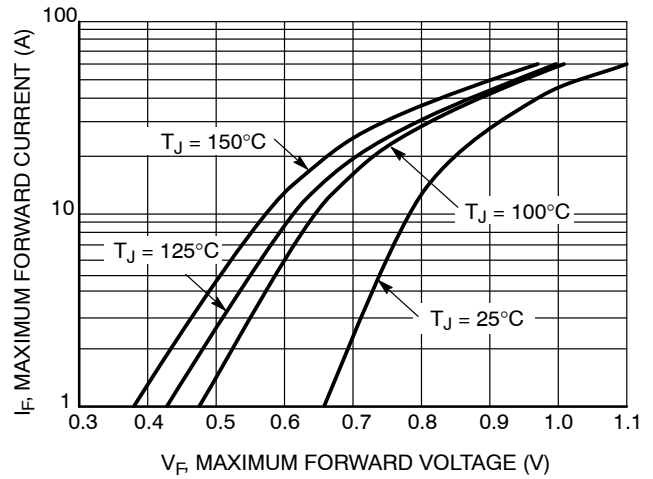


Figure 2. Maximum Forward Voltage

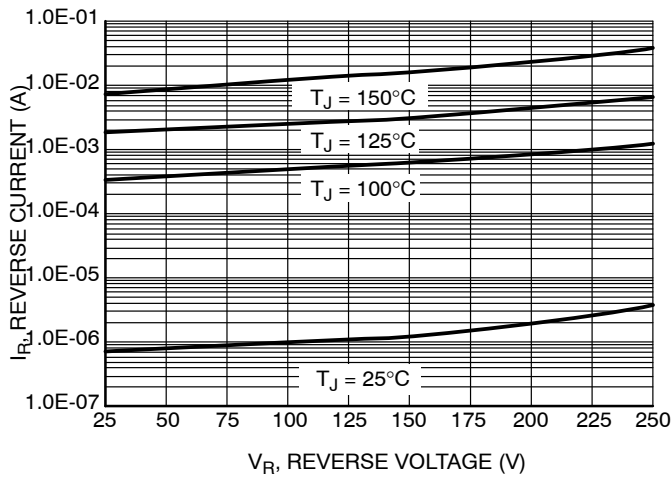


Figure 3. Typical Reverse Current

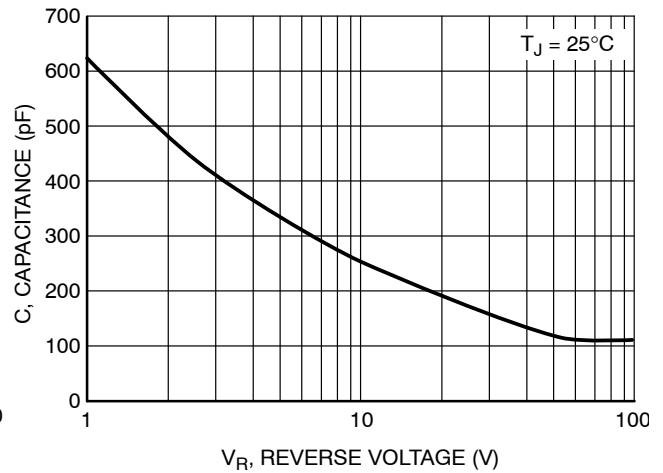


Figure 4. Typical Capacitance

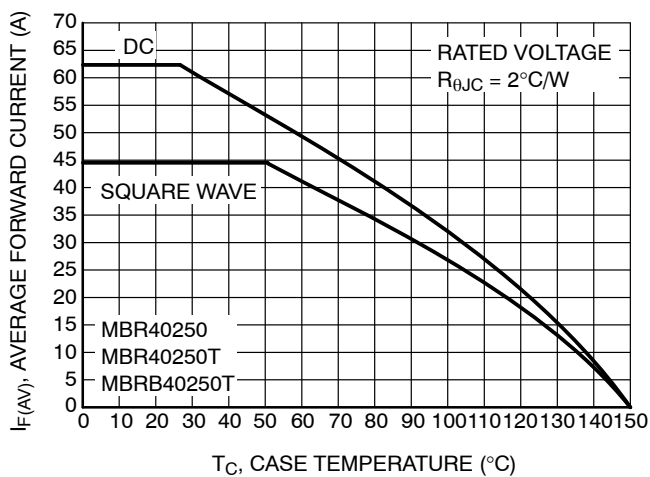


Figure 5. Current Derating (Case) for MBR40250, MBR40250T and MBRB40250T

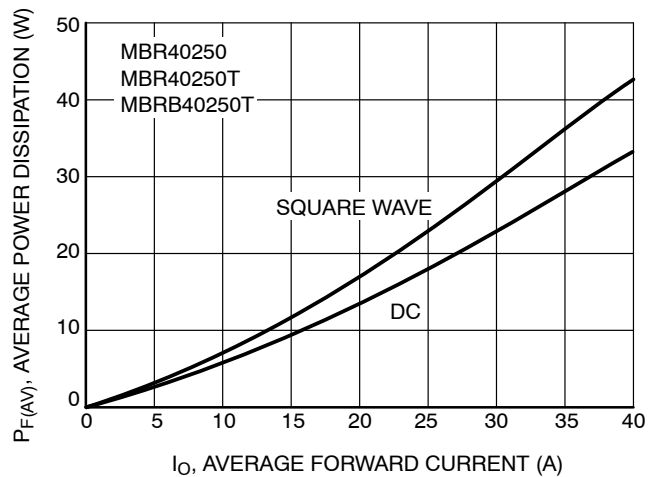


Figure 6. Forward Power Dissipation for MBR40250, MBR40250T and MBRB40250T

MBR40250, MBR40250T, MBRF40250T, MBRB40250T

TYPICAL CHARACTERISTICS

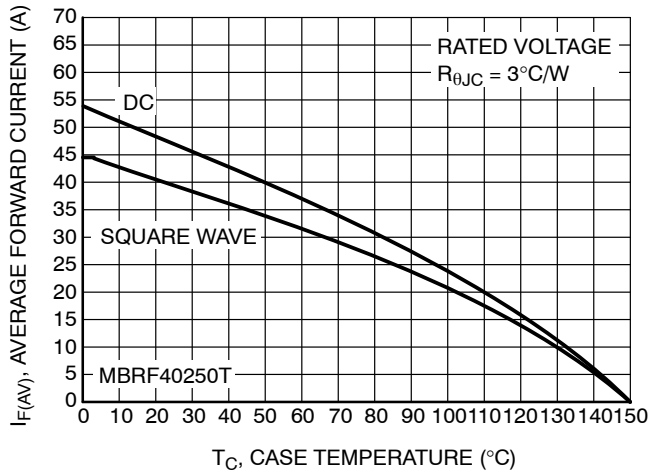


Figure 7. Current Derating (Case) for MBRF40250T

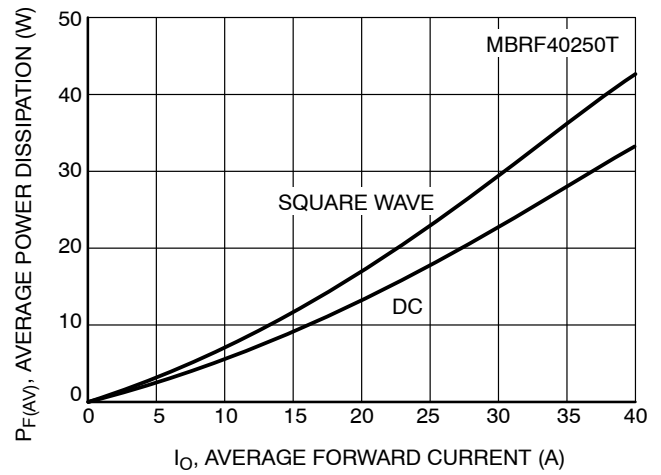


Figure 8. Forward Power Dissipation for MBRF40250T

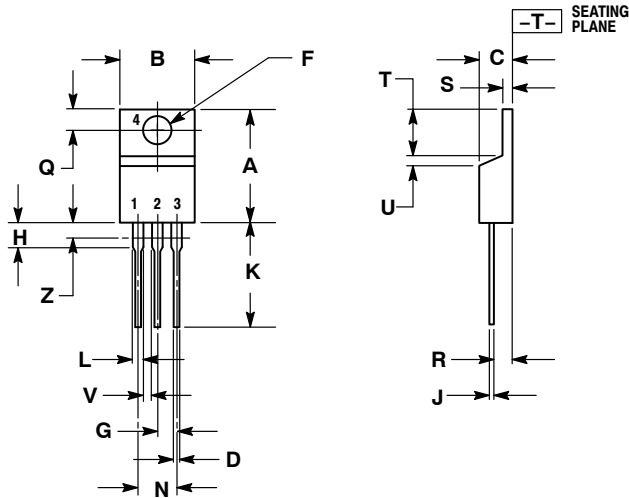
ORDERING INFORMATION

Device	Package	Shipping [†]
MBR40250G	TO-220AC (Pb-Free)	50 Units / Rail
MBR40250TG	TO-220AB (Pb-Free)	50 Units / Rail
MBRF40250TG	TO-220 FULLPACK (Pb-Free)	50 Units / Rail
MBRB40250TG	D ² PAK (Pb-Free)	50 Units / Rail
MBRB40250TT4G	D ² PAK (Pb-Free)	800 Units / Tape & Reel

MBR40250, MBR40250T, MBRF40250T, MBRB40250T

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 ISSUE AF



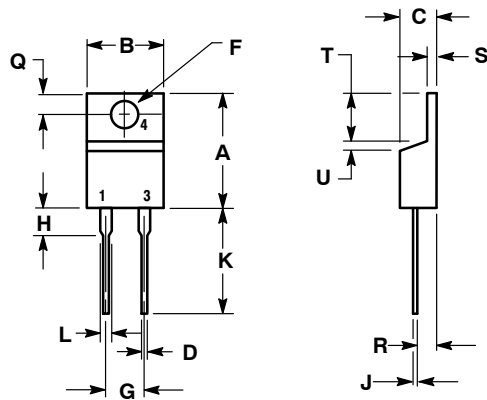
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.570	0.620	14.48	15.75
B	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
H	0.110	0.155	2.80	3.93
J	0.014	0.025	0.36	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	---	1.15	---
Z	---	0.080	---	2.04

STYLE 6:

1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

TO-220AC CASE 221B-04 ISSUE E



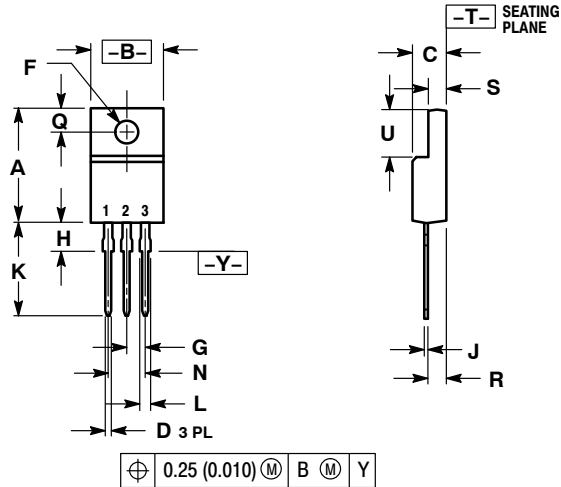
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.595	0.620	15.11	15.75
B	0.380	0.405	9.66	10.29
C	0.160	0.190	4.06	4.82
D	0.025	0.035	0.64	0.89
F	0.142	0.161	3.61	4.09
G	0.190	0.210	4.83	5.33
H	0.110	0.130	2.79	3.30
J	0.014	0.025	0.36	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.14	1.52
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.14	1.39
T	0.235	0.255	5.97	6.48
U	0.000	0.050	0.000	1.27

MBR40250, MBR40250T, MBRF40250T, MBRB40250T

PACKAGE DIMENSIONS

TO-220 FULLPAK CASE 221D-03 ISSUE J



NOTES:

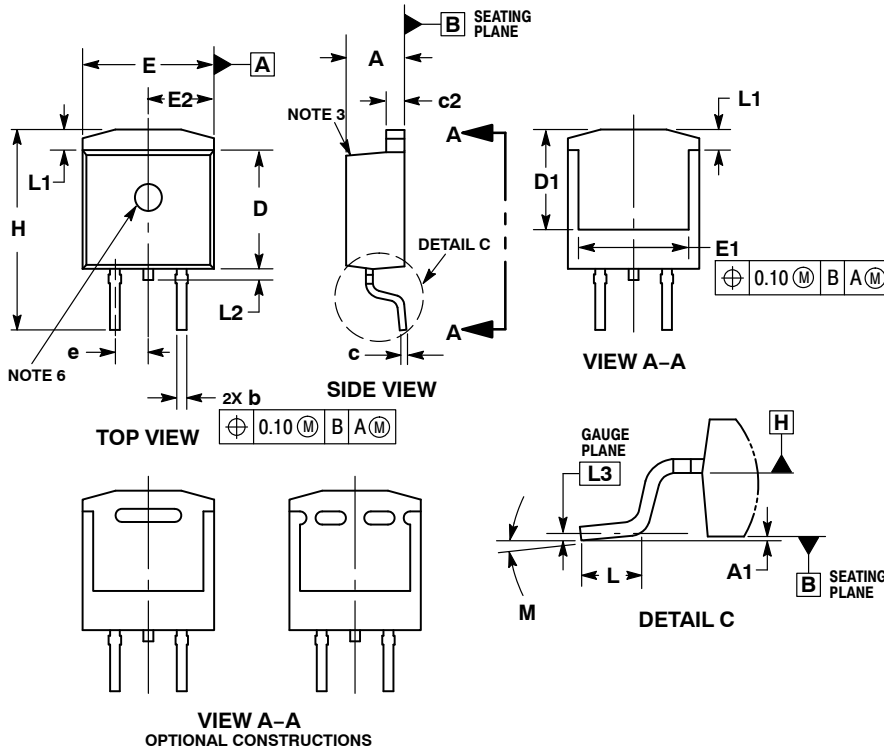
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH
3. 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.617	0.635	15.67	16.12
B	0.392	0.419	9.96	10.63
C	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100 BSC		2.54 BSC	
H	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
N	0.200 BSC		5.08 BSC	
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88

MBR40250, MBR40250T, MBRF40250T, MBRB40250T

PACKAGE DIMENSIONS

D²PAK 3 (TO-263, 3-LEAD) CASE 418AJ ISSUE A

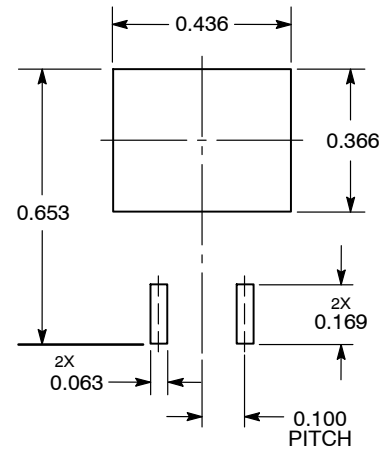


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. CHAMFER OPTIONAL
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.005 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AT DATUM H.
5. THERMAL PAD CONTOUR IS OPTIONAL WITHIN DIMENSIONS E, L1, D1 AND E1.
6. OPTIONAL MOLD FEATURE

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.160	0.190	4.06	4.83
A1	0.000	0.010	0.00	0.25
b	0.020	0.039	0.51	0.99
c	0.012	0.029	0.30	0.74
c2	0.045	0.065	1.14	1.65
D	0.330	0.380	8.38	9.65
D1	0.260	---	6.60	---
E	0.380	0.420	9.65	10.67
E1	0.245	---	6.22	---
e	0.100 BSC		2.54 BSC	
H	0.575	0.625	14.60	15.88
L	0.070	0.110	1.78	2.79
L1	---	0.066	---	1.68
L2	---	0.070	---	1.78
L3	0.010 BSC		0.25 BSC	
M	0°	8°	0°	8°

RECOMMENDED SOLDERING FOOTPRINT



DIMENSIONS: INCHES

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